



# Product Change Notification

## 109285 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 109285 - 00  
**Change Title:** Intel® 3100 Chipset (Whitmore Lake), PCN 109285-00, Transport Media, Tray Change  
**Date of Publication:** April 1, 2009

## Key Characteristics of the Change:

Transport Media

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	May 01, 2009
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## Description of Change to the Customer:

In order to provide better protection to our products, Intel is making the following changes to the 3100 Chipset Tray:

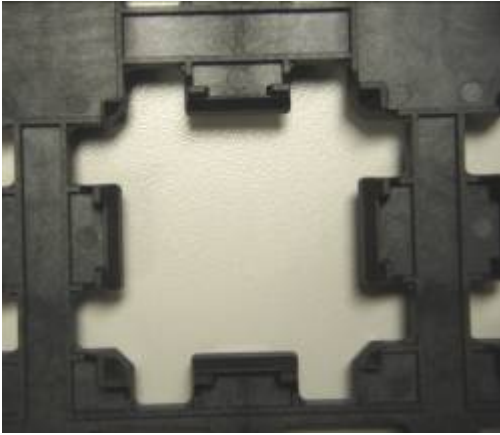
- 1) Tray pocket design change to enclosed structure.
- 2) Tray thickness reduction from 10.16mm to 6.35mm

## Current Tray part# 500056409

Entire tray view

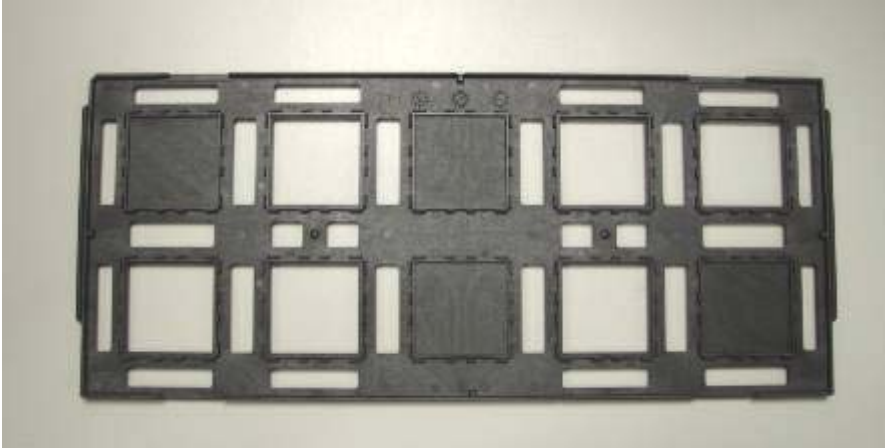


Pocket view

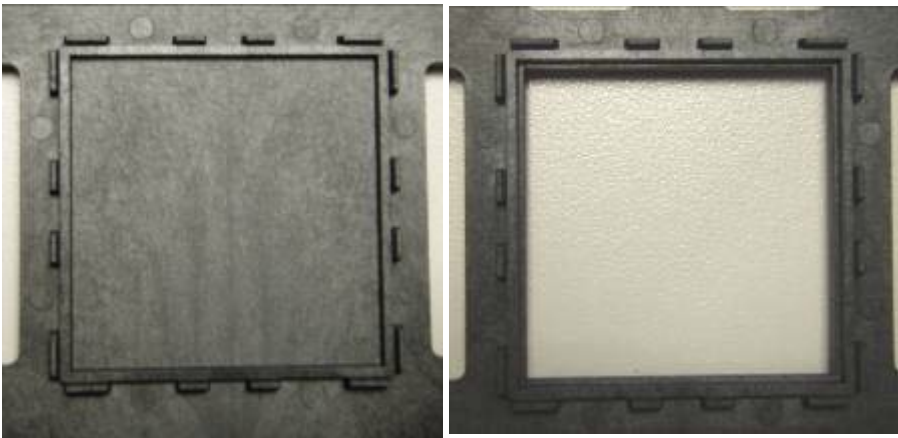


**New Tray part #500124451**

Entire Tray View



Pocket View



## Thickness difference



NEW TRAY

CURRENT TRAY

### Customer Impact of Change and Recommended Action:

Intel anticipates some impact to the customers. The new tray design is optimized with an enclosed structure, providing a more robust protection to products while reducing the tray's thickness. The units per tray quantity will increase from 14 to 22 and therefore the full box quantity will increase from 140 to 220, resulting in less storage space for Intel and Customers. New orders will be made in full box qty of 220.

Customers may want to notify their receiving department of the change and modify the equipment setting due to the tray thickness reduction.

Customers may continue to receive current tray until inventory is depleted. However, after May 1, 2009 all orders taken will be shipped in the new tray.

### Products Affected / Intel Ordering Codes:

Marketing Name	Stepping	Pre Conversion Product Code	Pre Conversion S-Spec	Pre Conversion MM#
Intel® 3100 Chipset	A-1	LE3100MICH	S L9PU	883904

### Reference Documents / Attachments:

Document:

Location #:

### PCN Revision History:

Date of Revision:

April 1, 2009

Revision Number:

00

Reason:

Originally Published PCN